

## Press Release

### Heraeus Electronics and Bosch Sign Patent and Know-How License Agreement for Inorganic Potting Technology at PCIM Europe Exhibition

Heraeus Electronics and Robert Bosch GmbH have signed a patent and know-how license agreement at the PCIM Europe exhibition in Nuremberg, Germany. The agreement allows Heraeus Electronics to access a valuable patent portfolio from Bosch to accelerate the development of their inorganic potting compound, CemPack®, for encapsulation of power modules.

“The combination of expertise between Heraeus and Bosch enables a new type of encapsulants that will bring power electronic packages to the next level so that these packages can unfold the full potential of a new generation of semiconductors,” said Dr. Klemens Brunner, Head of Heraeus Electronics.

The encapsulation material offers superior thermal conductivity ( $>5 \text{ W/m/K}$ ) and extreme temperature resistance (up to  $300^\circ\text{C}$ ), enabling increased power densities and improved reliability. The license agreement also allows the extension of the application spectrum to encapsulation of passive components (magnetics, capacitors, or resistors), electric motors (stators), or other devices where a thermal bridge to a heat sink is required while ensuring protection against the environment.



“Collaborations like these show the importance of open innovation to speed up development cycles and it is a great example for the innovation power of Heraeus,” said Michael Jörger, Head of Business Line Power Electronic Materials at Heraeus Electronics.

“We are excited to share our knowledge and IP of this new technology with Heraeus to deliver inorganic potting compounds meeting the highest standards of performance and reliability. Like Bosch, Heraeus is committed to excellence and has a reputation of shaping the market with innovative products,” said Dr. Peter Wolfangel, EVP Corporate Sector Research and Advance Engineering at Bosch.

The agreement is significant given the increasing demand for power modules as key components of the transition towards electrification. With its existing material portfolio for packaging and interconnection of semiconducting power dies, Heraeus Electronics already offers cutting-edge solutions for power electronics such as sinter paste, DTS, and Ag-free AMB.

To learn more about Heraeus Electronics, visit [www.heraeus-electronics.com](http://www.heraeus-electronics.com).

### **About Heraeus**

The Heraeus Group is a broadly diversified and globally leading family-owned technology company, headquartered in Hanau, Germany. The company's roots go back to a family pharmacy started in 1660. Today, the Heraeus group includes businesses in the environmental, electronics, health and industrial applications sectors. Customers benefit from innovative technologies and solutions based on broad materials expertise and technological leadership.

In the 2021 financial year, the FORTUNE Global 500 listed group generated revenues of €29.5 billion (US\$34.9 billion\*) with approximately 16,200 employees in 40 countries. Heraeus is one of the top 10 family-owned companies in Germany and holds a leading position in its global markets.

### **About Heraeus Electronics**

Heraeus Electronics is a leading manufacturer of materials for the assembly and packaging of devices in the electronics industry. The company develops material solutions for the automotive, power electronics and advanced semiconductor packaging market and offers its customers a broad product portfolio - from materials and material systems to services.

### **Media Contact**

Christian Spielmann

Press Contact Heraeus Electronics

0049 6181 35-4326

[christian.spielmann@heraeus.com](mailto:christian.spielmann@heraeus.com)